

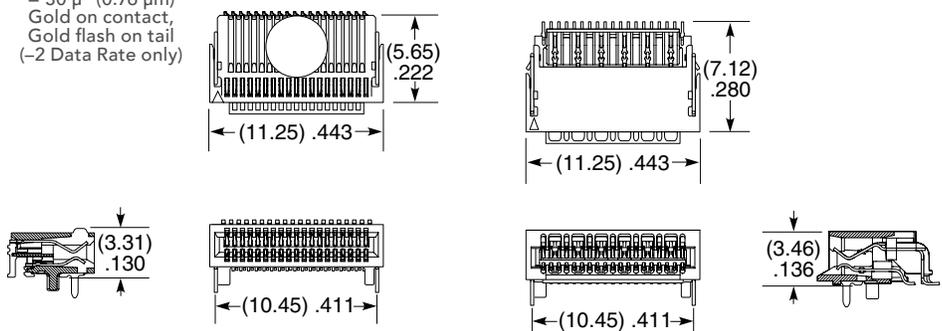
RUGGED MICRO FLYOVER® SOCKET SYSTEM

UEC5	NO. OF POSITIONS	DATA RATE	PLATING OPTION	D	RA	WELD TAB	OPTION	PACKAGING
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	-019 (Per Row)	-1 = Up to 16 Gbps -2 = 28 Gbps+	-H = 30 μ" (0.76 μm) Gold on contact, Gold flash on tail (-1 Data Rate only) -H = 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail (-2 Data Rate only) -HFL = 30 μ" (0.76 μm) Gold on contact, Gold flash on tail (-2 Data Rate only)			-1 = Through-hole -2 = Surface Mount (Data Rate -1 only)	Leave blank for -2 Data Rate -A = Alignment Pin (Available with Data Rate -1 only)	Leave blank for Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
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SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
BeCu
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp Range:
-55 °C to +125 °C



UEC5-019-1-X-D-RA-1

UEC5-019-2-X-D-RA-1

PROCESSING

SMT Lead Coplanarity:
(0.10 mm) .004" max.

Note:
PCB footprints are not interchangeable for -1 and -2 data rate versions.

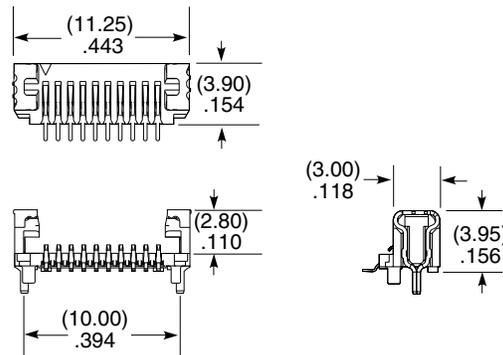
View complete specifications at: samtec.com?UEC5-1 & samtec.com?UEC5-2

UCC8	NO. OF POSITIONS	1	PLATING OPTION	S	WELD TAB	A	PACKAGING
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	-010		-H = 30 μ" (0.76 μm) Gold on contact, Gold flash on tail		-1 = Through-hole		Leave blank for Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
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SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
BeCu
Weld Tab:
Copper Alloy
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp Range:
-55 °C to +125 °C



PROCESSING

SMT Lead Coplanarity:
(0.10 mm) .004" max.

Note:
Some sizes, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?UCC8